

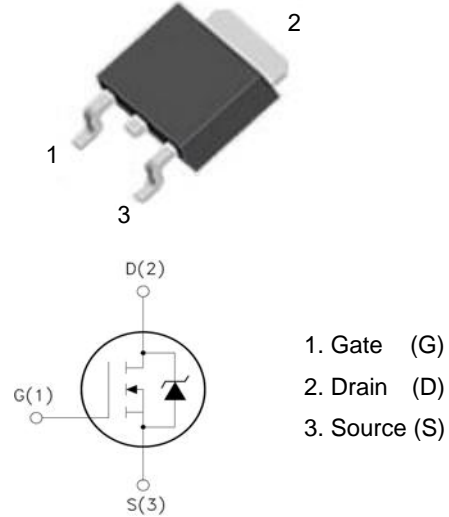


## XXW10N50

### Features

- Low Intrinsic Capacitances
- Excellent Switching Characteristics
- Extended Safe Operating Area
- Unrivalled Gate Charge : 28 nC (Typ.)
- $V_{DSS}=500V, I_D=10A$
- Lower  $R_{DS(on)} : 0.70 \Omega$  (Max) @  $V_G=10V$
- 100% Avalanche Tested

TO-252



### Absolute Maximum Ratings (Ta=25°C unless otherwise noted)

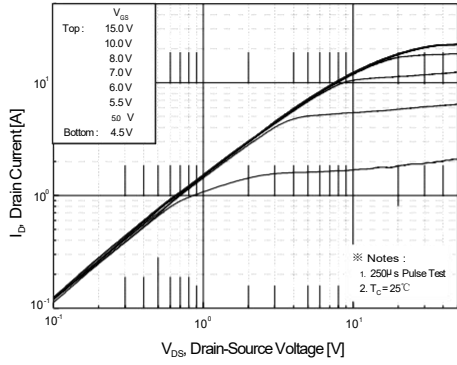
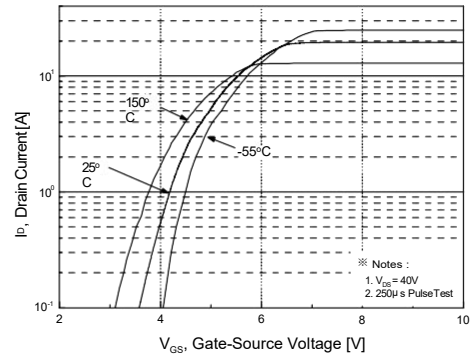
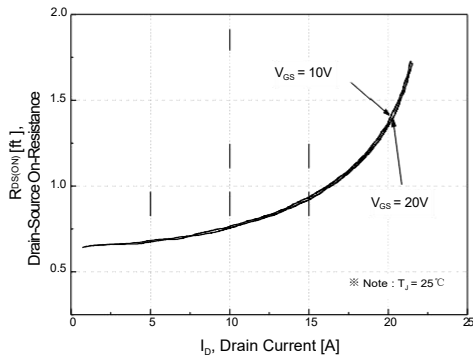
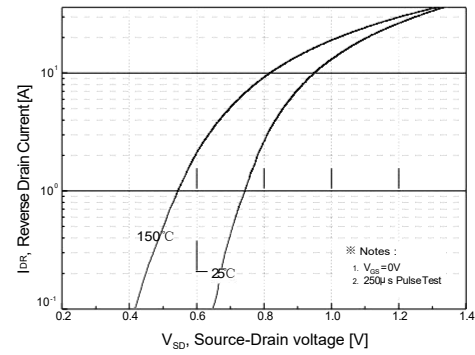
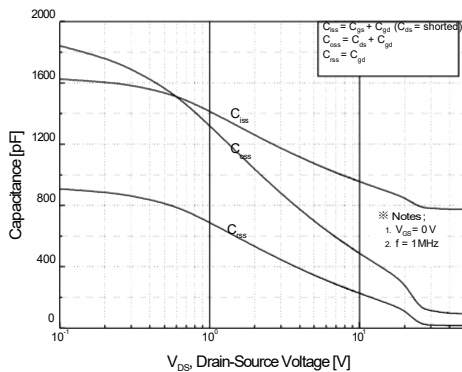
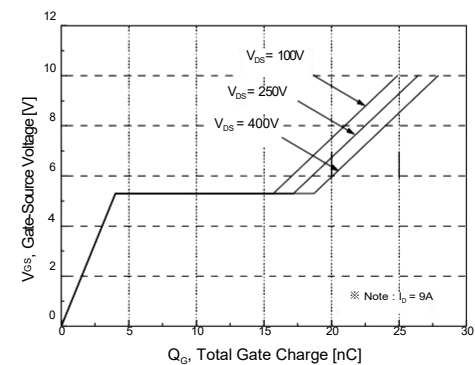
Symbol	Parameter	Value	Unit
$V_{DSS}$	Drain-Source Voltage	500	V
$I_D$	Drain Current	$T_j=25^\circ C$	10
		$T_j=100^\circ C$	5.7
$V_{GSS}$	Gate-Source Voltage	$\pm 30$	V
$E_{AS}$	Single Pulse Avalanche Energy (note1)	190	mJ
$I_{AR}$	Avalanche Current (note2)	9.0	A
$P_D$	Power Dissipation ( $T_j=25^\circ C$ )	30	W
$T_j$	Junction Temperature(Max)	150	$^\circ C$
$T_{stg}$	Storage Temperature	-55~+150	$^\circ C$
TL	Maximum lead temperature for soldering purpose, 1/8" from case for 5 seconds	300	$^\circ C$

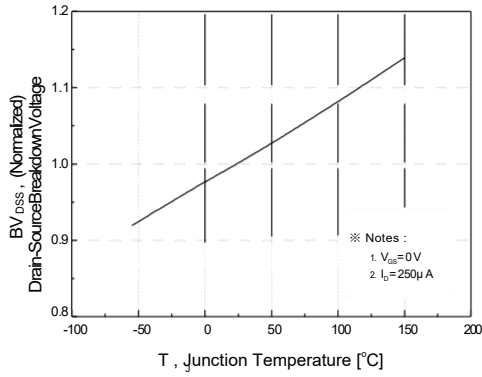
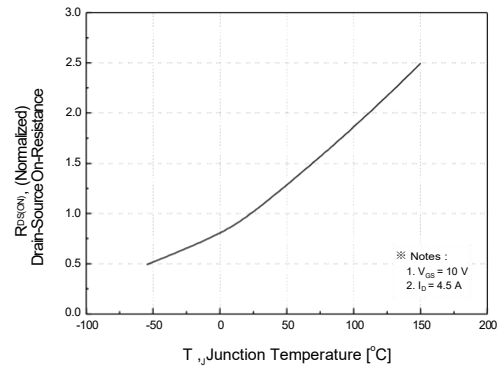
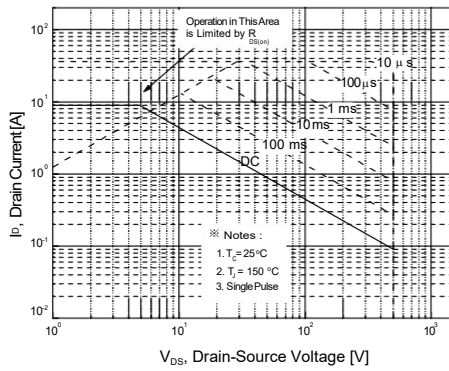
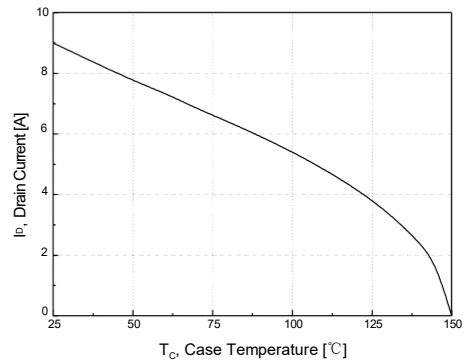
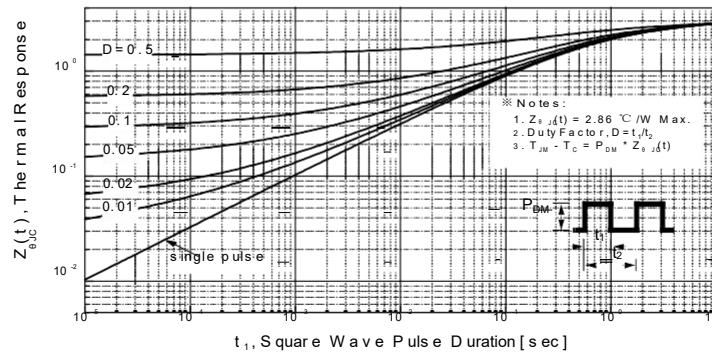
### Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case	-	1.88	$^\circ C/W$
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	-	62.5	$^\circ C/W$

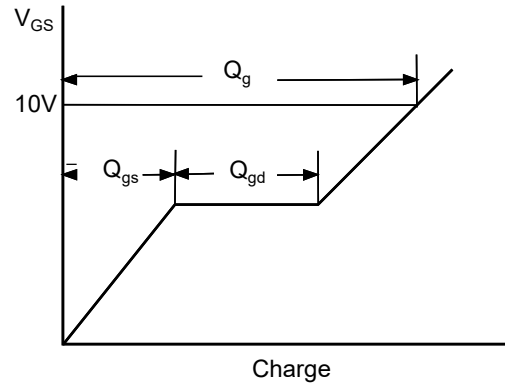
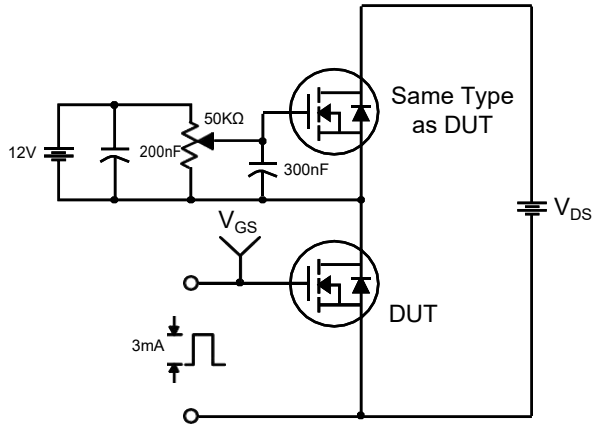
**Electrical Characteristics** (Ta=25°C unless otherwise noted)

Symbol	Parameter	Test Condition	Min.	Typ.	Max	Units
<b>Off Characteristics</b>						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	ID=250 μ A, VGS=0	500	--	--	V
ΔBV <sub>DSS</sub> / ΔT <sub>J</sub>	Breakdown Voltage Temperature Coefficient	ID=250 μ A, Reference to 25°C	--	0.55	--	V/°C
IDSS	Zero Gate Voltage Drain Current	Vds=500V, Vgs=0V	--	--	1	μ A
		Vds=400V, Tc=125°C			10	μ A
IGSSF	Gate-body leakage Current, Forward	Vgs=+30V, Vds=0V	--	--	100	nA
IGSSR	Gate-body leakage Current, Reverse	Vgs=-30V, Vds=0V	--	--	-100	nA
<b>On Characteristics</b>						
V <sub>GS(th)</sub>	Gate Threshold Voltage	Id=250uA, Vds=Vgs	2	--	4	V
R <sub>DS(on)</sub>	Static Drain-Source On-Resistance	Id=4.5A, Vgs=10V	--	0.65	0.70	Ω
<b>Dynamic Characteristics</b>						
Ciss	Input Capacitance	VDS=25V, VGS=0, f=1.0MHz	--	1012	--	pF
Coss	Output Capacitance		--	160	--	pF
Crss	Reverse Transfer Capacitance		--	20	--	pF
<b>Switching Characteristics</b>						
Td(on)	Turn-On Delay Time	VDD=250V, ID=9A, RG=25 Ω (Note 3,4)	--	25	60	nS
Tr	Turn-On Rise Time		--	95	200	nS
Td(off)	Turn-Off Delay Time		--	55	120	nS
Tf	Turn-Off Fall Time		--	60	130	nS
Qg	Total Gate Charge	VDS=400, VGS=10V, ID=9A (Note 3,4)	--	28	36	nC
Qgs	Gate-Source Charge		--	7	--	nC
Qgd	Gate-Drain Charge			12.5	--	nC
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
I <sub>S</sub>	Maximun Continuous Drain-Source Diode Forward Current		--	--	9	A
I <sub>SM</sub>	Maximun Plused Drain-Source Diode Forward Current		--	--	36	A
V <sub>SD</sub>	Drain-Source Diode Forward Voltage	Id=9A	--	--	1.45	V
trr	Reverse Recovery Time	I <sub>S</sub> =9.0A, V <sub>GS</sub> =0V	--	300	--	nS
Qrr	Reverse Recovery Charge	di <sub>F</sub> /dt=100A/ μ S (Note3)	--	2.2	--	μ C
*Notes	1, L=8mH, IAS=9A, VDD=50V, RG=25Ω, Starting T <sub>J</sub> =25°C 2, Repetitive Rating : Pulse width limited by maximum junction temperature 3, Pulse Test : Pulse Width ≤ 300μs, Duty Cycle ≤ 2% 4, Essentially Independent of Operating Temperature					

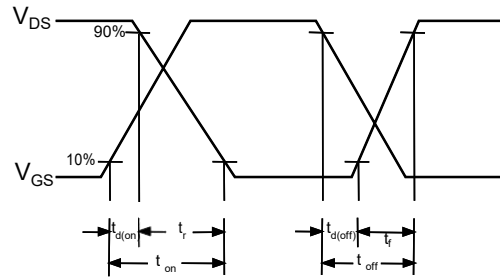
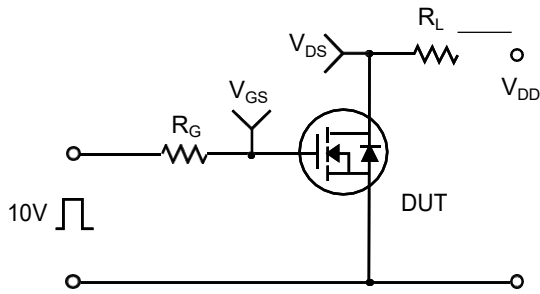
**Typical Characteristics**

**Figure 1. On-Region Characteristics**

**Figure 2. Transfer Characteristics**

**Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage**

**Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature**

**Figure 5. Capacitance Characteristics**

**Figure 6. Gate Charge Characteristics**

**Typical Characteristics (Continued)**

**Figure 7. Breakdown Voltage Variation vs Temperature**

**Figure 8. On-Resistance Variation vs Temperature**

**Figure 9-2. Maximum Safe Operating Area**

**Figure 10. Maximum Drain Current vs Case Temperature**

**Figure 11-2. Transient Thermal Response Curve**

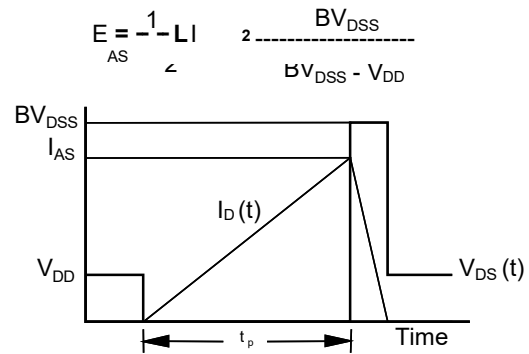
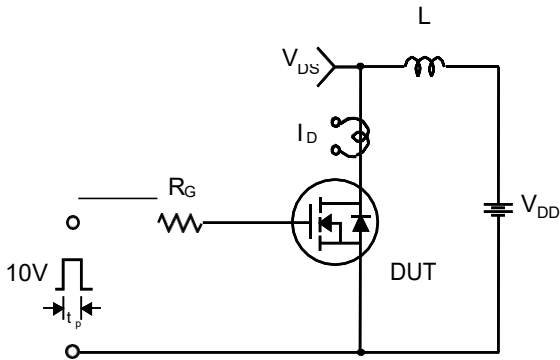
**Gate Charge Test Circuit & Waveform**



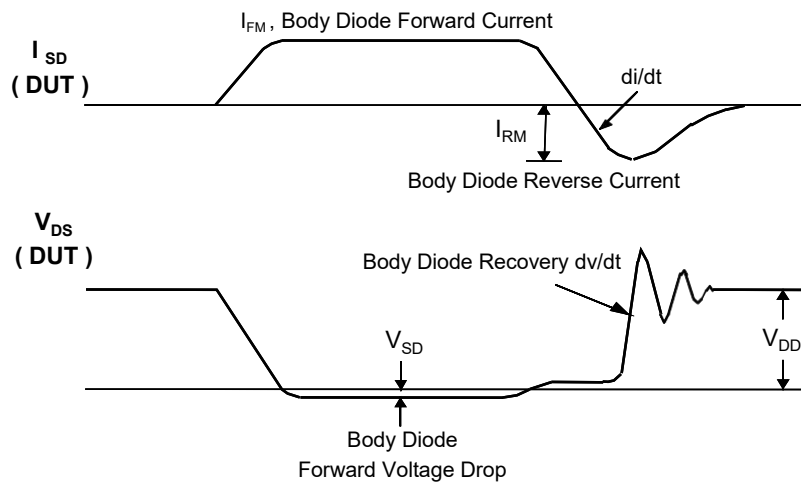
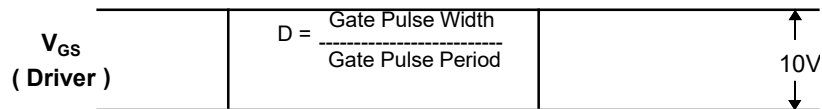
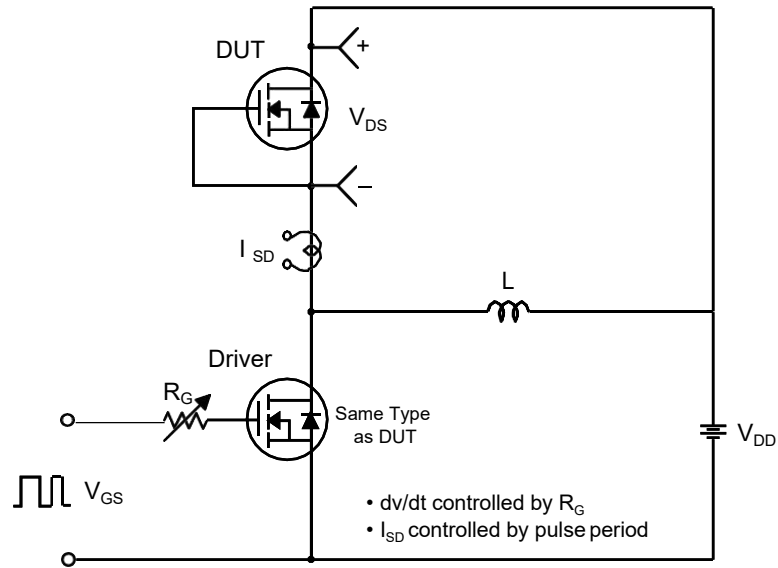
**Resistive Switching Test Circuit & Waveforms**



**Unclamped Inductive Switching Test Circuit & Waveforms**

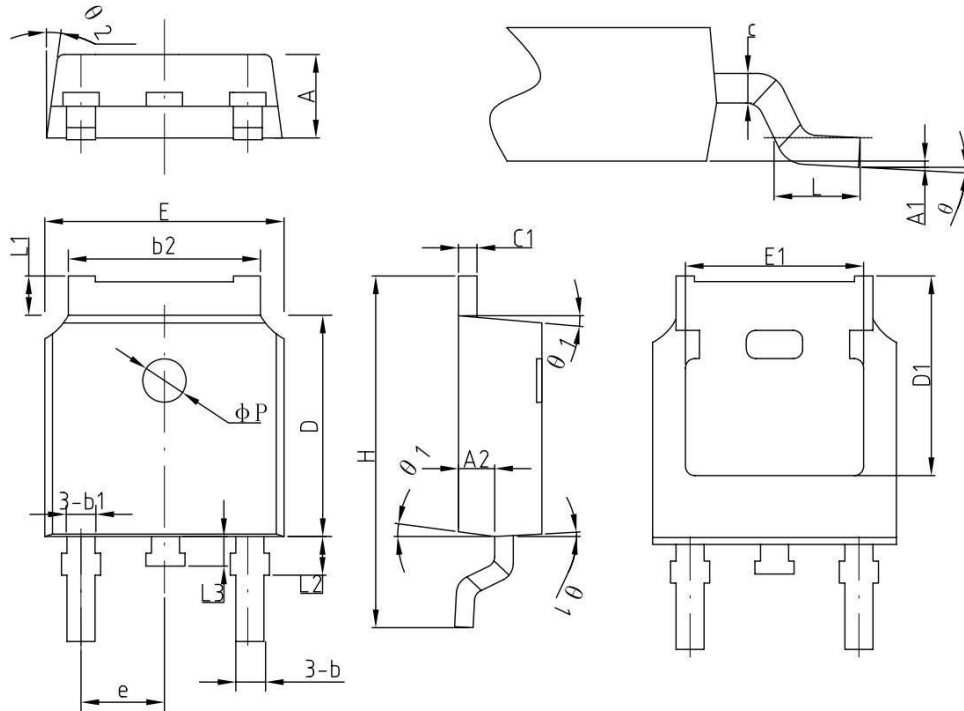


**Peak Diode Recovery dv/dt Test Circuit & Waveforms**



**Package Dimension**
**TO-252**

Unit: mm


 COMMON DIMENSIONS  
 (UNITS OF MEASURE=MILLIMETER)

SYMBOL	MIN	NOM	MAX
A	2.2	2.30	2.38
A1	0	—	0.10
A2	0.90	1.01	1.10
b	0.71	0.76	0.86
b1		0.76	
b2	5.13	5.33	5.46
c	0.47	0.50	0.60
c1	0.47	0.50	0.60
D	6.0	6.10	6.20
D1	—	5.30	—
E	6.50	6.60	6.70
E1	—	4.80	—
e	2.286BSC		
H	9.70	10.10	10.40
L	1.40	1.50	1.70
L1	0.90	—	1.25
L2		1.05	
L3		0.8	
$\phi P$		1.2	
$\theta$	0°	—	8°
$\theta_1$	5°	7°	9°
$\theta_2$	5°	7°	9°